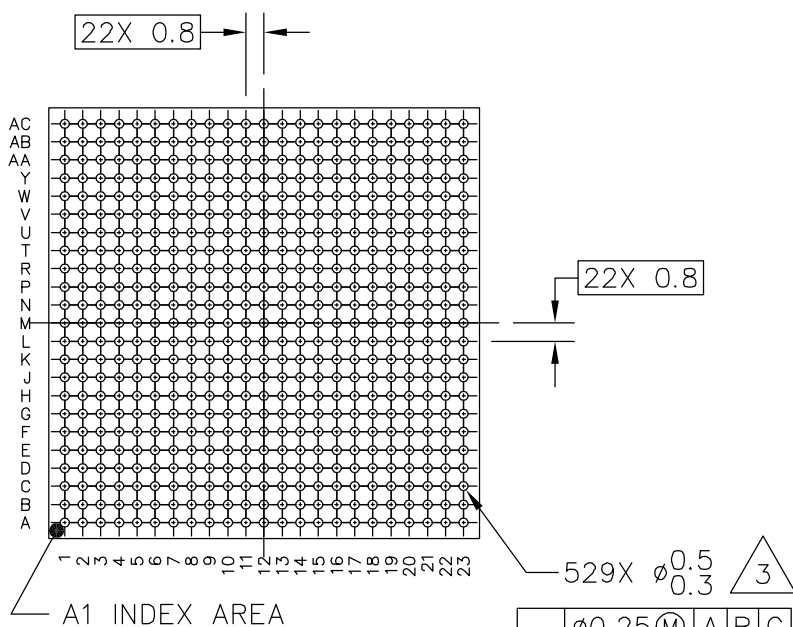
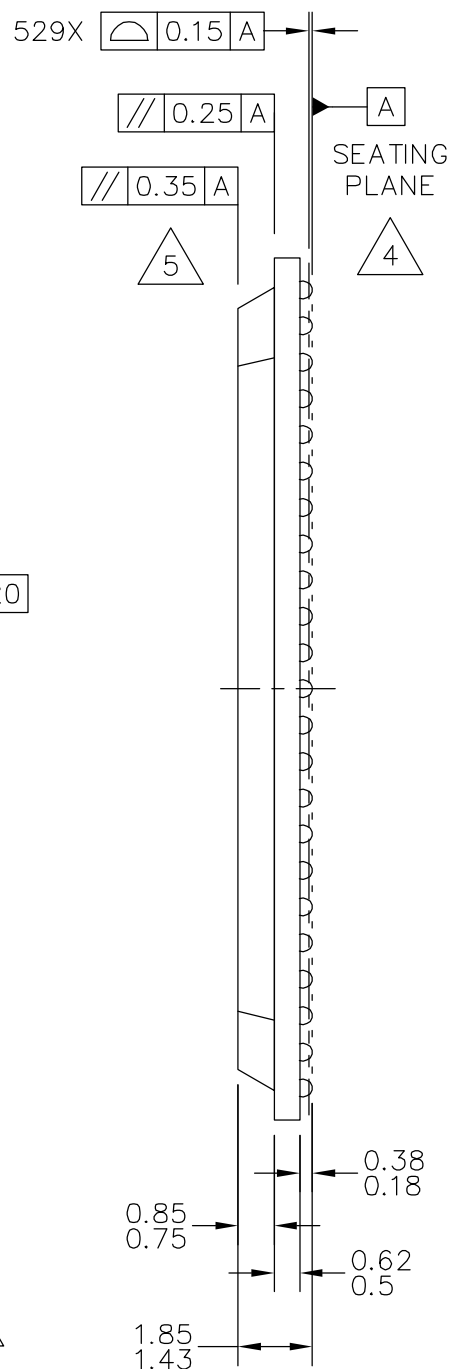
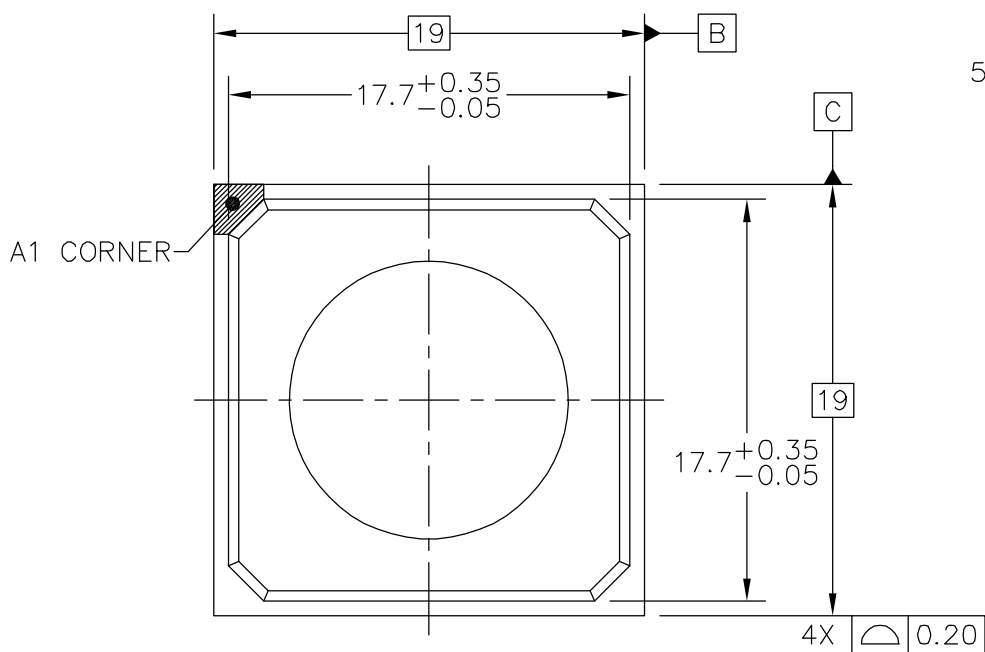




BOTTOM VIEW

SIDE VIEW

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TITLE: TEPBGA-II, 529 I/O, 19 X 19 PKG, 0.8 MM PITCH		DOCUMENT NO: 98ASA00167D	REV: 0
		CASE NUMBER: 2105-03	22 JUL 2011
		STANDARD: NON-JEDEC	

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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